Product End-of-Life Disassembly Instructions

Product Category: External Options

Marketing Name / Model: HP ZBook Studio G7 Mobile Workstation
[List multiple models if applicable.]

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [ ] screws [x] snaps [x] adhesive [x] other. Explain. NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>1</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords, Adapter</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs)</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

EL-MF877-00
Template Revision C

Last revalidation date 09-May-2018

HPI instructions for this template are available at EL-MF877-01
### Item Description | Notes | Quantity of items included in product
--- | --- | ---
already listed as a separate item above) |  | |
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | |
Components and waste containing asbestos |  | |
Components, parts and materials containing refractory ceramic fibers |  | |
Components, parts and materials containing radioactive substances |  | |

### 2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>Philip #1</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>Philip #0</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>Philip #T5</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove Log Low
2. Remove Battery pack
3. Remove FAN & Thermal module
4. Remove Motherboard
5. Remove Speaker Rear & Cavity
6. Remove Hinge for the Logic Up
7. Remove Hinge Cap
8. Remove Both Hinge
9. Remove LCD Cover
10. Remove Antenna
11. Remove EDP cable / TS / Camera module / Sensor PCB

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Step 1 Remove Log Low

Step 2 Remove Battery pack

Step 3 Remove FAN & Thermal module

Step 4 Remove Motherboard

Step 5 Remove Speaker Rear & Cavity

Step 6 Remove Hinge for the Logic Up

HPI instructions for this template are available at EL-MF877-01
Step 7: Remove Hinge Cap

Step 8: Remove Both Hinge

Step 9: Remove LCD Cover

Step 10: Remove Antenna

Step 11: Remove EDP cable / TS / Camera module / Sensor PCB

HPI instructions for this template are available at EL-MF877-01